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Volume 22 Number 2

**Contributions in Engineering Education Research,
Engineering Education Policy, Gender Studies, Information
Technology, Electrical and Electronic Engineering, Industrial
Engineering, Manufacturing Engineering, Engineering Design,
Engineering Graphics, Thermal Engineering, Engineering
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The International Journal of ENGINEERING EDUCATION

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Published 6 per annum

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The International Journal of ENGINEERING EDUCATION

AIMS AND SCOPE

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Meijknecht—The Five Saints of Electrical Engineering

Bailey, Szabo—Assessing Engineering Design Process Knowledge

Cuddihy—Assessing One Aspect of Design Learning: Qualitative Analysis of Students' Design Rationales

Socha, Walter—Is Designing Software Different From Designing Other Things?

Healy—Restructuring an Engineering Core Course to Prepare Students for Design Experiences

Obarski, Soled—Engineers as Inquiry Practitioners

Ogot, Okudan—Systematic Creativity Methods in Engineering Education: A Learning Styles Perspective

Agogino *et al.*—Triangulation of Indicators of Successful Student Design Teams

Turns *et al.*—Tackling the Research-to-Teaching Challenge in Engineering Design Education: Making the Invisible Visible

Terpenny *et al.*—Utilizing Assistive Technology Design Projects and Interdisciplinary Teams to Foster Inquiry and Learning in Engineering Design

Contero *et al.*—Learning Support Tools for Developing Spatial Abilities in Engineering Design

Walker *et al.*—Design Scenarios as an Assessment of Adaptive Expertise

Holmes, Spilker—Linking Undergraduate Mathematics Education with Engineering

Caine *et al.*—Developing an Industrially Supported Sports Technology Degree: A Case Study

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Bovea *et al.*—Work Placements and the Final Year Project: A Joint Experience in the Industrial Engineering Degree

Sobek—System-Level Design: A Missing Link?

Ohland, Summers—Teaching Design using Multiple Hierarchical Engineering Education Models

Lewis, Magleby, Todd—Learning to Design Products in Environments with Limited Design Traditions

Evans *et al.*—The Idea to Product Program: An Educational Model Uniting Emerging Technologies, Student Leadership and Societal Applications

Garcia-Beltran—Web assisted self-assessment in computer programming learning using AulaWeb

Slozak, Polycarpou—Engineering Outreach to Cub Scouts with Hands-on Activities Pertaining to the Pinewood Derby Car Race

Perez—Multimedia System for the Teaching of Proximity Sensors

Nasrazadani—Design and Construction of a Heat Exchanger Analyzer for an Undergraduate Thermal Fluid Laboratory